

**Amendments to the Claims:**

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

1. (Currently Amended) A method of removing adhesive film from a substrate, the adhesive film comprising first and second ends defining a length and a width transverse to the length, the method comprising:

applying tension over the width of the adhesive film to remove the adhesive film from the substrate along a release line;

transferring the tension onto the substrate in the form of a compressive force, wherein the compressive force is applied to the substrate at a distance from the release line;

varying the distance between the compressive force and the release line; and

advancing the release line and the compressive force towards the second end of the adhesive film, whereby the adhesive film is removed from the substrate.

2. Cancelled

3. Cancelled

4. (Previously Presented) A method according to claim 1, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.

5. (Previously Presented) A method according to claim 1, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.

6. Cancelled

7. (Currently Amended) A method according to claim 1 6, wherein varying the distance between the compressive force and the release line comprises varying the tension applied to the adhesive film.

8. (Original) A method according to claim 1, wherein the compressive force is applied to the substrate by a roll.

9. (Original) A method according to claim 1, wherein applying tension over the width of the adhesive film comprises attaching the first end of the adhesive film to a winding roll and winding the adhesive film thereon.

10. (Original) A method according to claim 9, wherein the compressive force is applied to the substrate by a support roll, and further wherein the winding roll and the support roll are located a fixed distance apart.

11. (Original) A method according to claim 1, further comprising heating the adhesive film before removing the adhesive film from the substrate along the release line.

12. (Currently Amended) A method of removing adhesive film from a substrate, the adhesive film comprising first and second ends defining a length and a width transverse to the length, the method comprising:

attaching the first end of the adhesive film to a winding device;

rotating the winding device to apply tension over the width of the adhesive film to

remove the adhesive film from the substrate along a release line;

transferring the tension applied to the adhesive film onto the substrate in the form of a compressive force, with the compressive force being applied to the substrate by the winding device and wherein the compressive force is applied to the substrate at a distance from the release line;

varying the distance between the compressive force and the release line; and

advancing the release line towards the second end of the adhesive film while winding the adhesive film on the winding device, whereby the adhesive film is removed from the substrate.

13. (Original) A method according to claim 12, wherein the adhesive film comprises a large-scale adhesive film.

14. Cancelled

15. Cancelled

16. Cancelled

17. (Previously Presented) A method according to claim 12, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.

18. (Previously Presented) A method according to claim 12, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.

19. Cancelled

20. (Currently Amended) A method according to claim 12 ~~19~~, wherein varying the distance between the compressive force and the release line comprises varying the speed at which the winding device is rotated.

21. (Original) A method according to claim 12, further comprising heating the adhesive film before removing the adhesive film from the substrate along the release line.

22. Cancelled

23. Cancelled

24. Cancelled

25. Cancelled